


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ADG/22/13500	
1.3 Title of PCI	Test pattern relocation from inner dice to scribing line	
1.4 Product Category	SiC	
1.5 Issue date	2022-06-15	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio Maria FERRARA
2.1.2 Marketing Manager	Michele MACAUDA, Marcello SGROI
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Mask Frame : introduction of new structure or never tested structure, change of die scribe separation or scribe line width	Shenzhen

4. Description of change

	Old	New
4.1 Description	For each litho mask step a die is sacrificed for test pattern structure	Moving the test pattern structures to the scribe line will increase the wafer gross
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	To grant a better service continuity
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	by new FG
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7. Timing / schedule

7.1 Date of qualification results	2022-06-09
7.2 Intended start of delivery	2022-06-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

13500 Public product.pdf
13500 PCI TEG GEN1 and GEN2.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SCTH40N120G2V7AG	

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